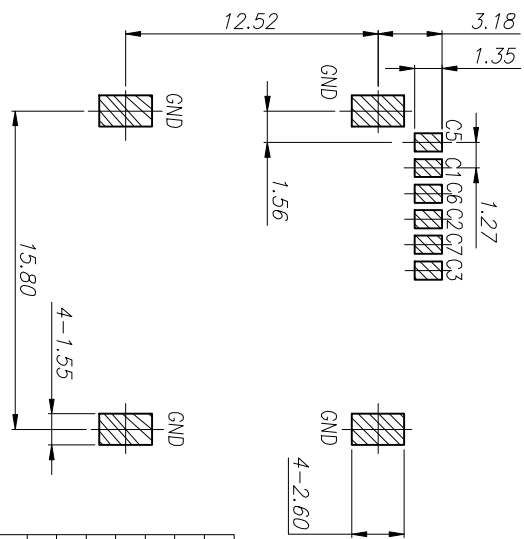
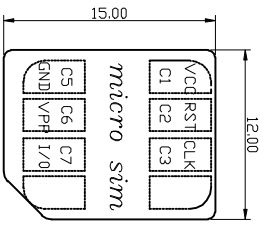
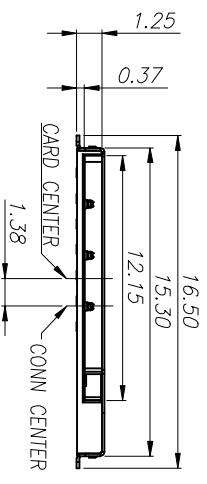
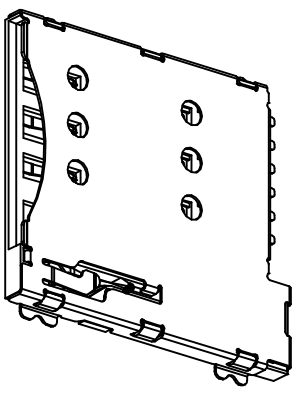
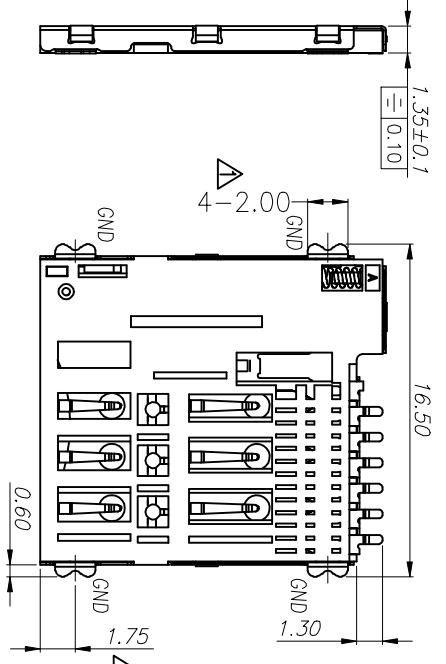
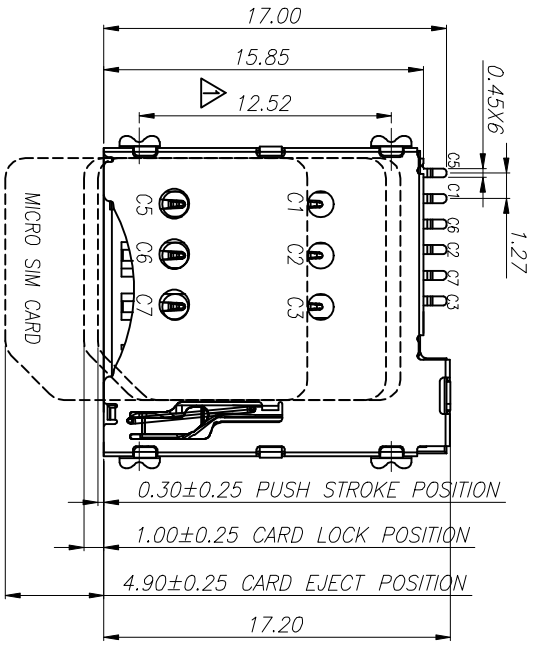
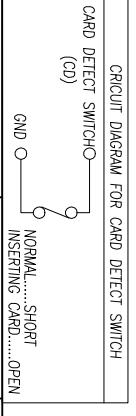


REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	20140903	wen		changyong
A1		更改外形轮廓间距和高度	20151022	wen		changyong



SIM pin Assignment	PIN#	Name
	C1	VCC
	C2	RST
	C3	CLK
	C5	GND
	C6	VPP
	C7	I/O

CIRCUIT TRACE KEEP OUT AREA
 SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



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MILLIMETERS	INCH	UNITS	MM
X ± 2	X ±	MATL	SEE NOTES
X ± 0.30	XX ±	FINISH	SEE NOTES
XXX ± 0.25	XXX ±	APPD:	wenchangyong
XXX ± 0.15	XXXX ±	CHKD:	
		DR:	
		DWG NO.:	MRC-SM05-135-0011
		PART NUMBER:	MICRO-SIM 4-PIN/5V/1.8V/1.38
		SCALE	1:1
		SHEET	1/2
		REV.	A1

NOTES:
MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0
 Contacts: Copper Alloy
 SMT: SOLDERLESS
PLATING:
 TERMINAL:
 CONTACT AREA: GOLD PLATE
 SOLDER AREA: NICKEL TIN PLATING
 UNDER PLATE: NICKEL
 SMT: NICKEL OVER ALL
 SOLDER AREA: GOLD PLATE
Electrical:
 Current Rating: 4 mA max.
 Voltage Rating: 5V DC MAX.
 Ambient Temperature Range: -20° C~+85° C
 Storage Temperature Range: -40° C~+125° C
 Ambient Humidity Range: 5% to 95% R.H. max.
 Contact Resistance: 100mΩ max.
 Insulation Resistance: 1000MΩ min. @50V DC
 Dielectric Withstanding Voltage: 50V AC
 Rating Cycle: 100 Insertions
 Temperature: 20° C ±5°